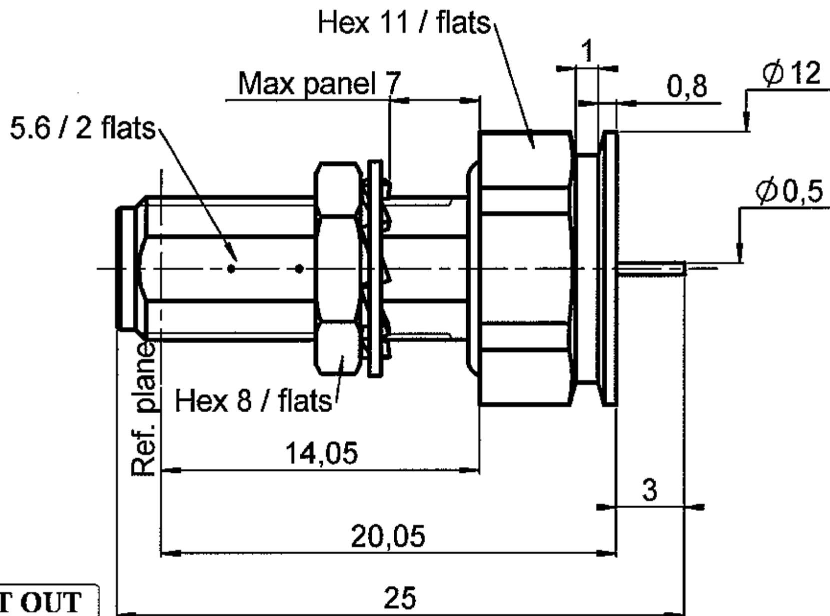
BULKHEAD JACK RECEPTACLE

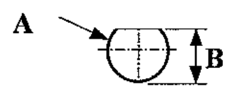
PANNEL SEAL - WITH CYLINDRICAL CONTACT

R124.580.508

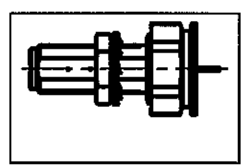
Series : **SMA-COM**



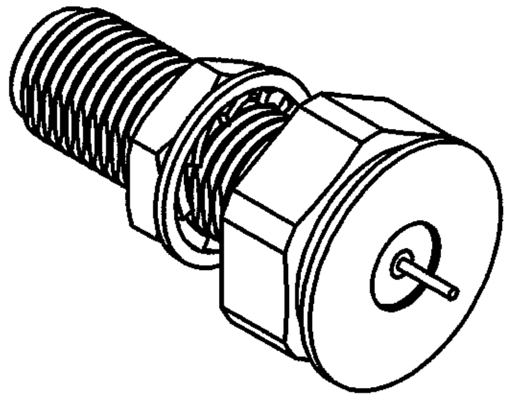
PANEL CUT OUT



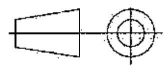
	mm	
	Maxi	**mini**
A	**6.5**	**6.4**
B	**6.15**	**6**



SCALE 1/1



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (µm)
BODY	**BRASS**	**TIN 3 OVER NICKEL 2**
CENTER CONTACT	**BERYLLIUM COPPER**	**GOLD 1.3 OVER NICKEL 2**
OUTER CONTACT	-	-
INSULATOR	**PTFE**	
GASKET	**SILICONE RUBBER**	
OTHERS PARTS	**BRASS**	**TIN 3 OVER NICKEL 2**
-	-	-
-	-	-

Issue : 0504 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

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PACKAGING

Standard	Unit	Other
1	-	**Contact us**

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance		**50**	Ω
Frequency		**0-18**	GHz
VSWR	**1.08** +	**0.003**	x F(GHz) Maxi
Insertion loss		**0.05**	√F(GHz) dB Maxi
RF leakage	- (	**100**	- F(GHz)) dB Maxi
Voltage rating		**500**	Veff Maxi
Dielectric withstanding voltage		**1000**	Veff mini
Insulation resistance		**5000**	MΩ mini

ENVIRONMENTAL

Operating temperature	**-40/+105**	° C
Hermetic seal	**NA**	Atm.cm3/s
Panel leakage	**NA**	

OTHERS CHARACTERISTICS

Assembly instruction **NA**

Others :

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end	**15**	N mini
Axial force – Opposite end	**15**	N mini
Torque	**NA**	N.cm mini
Recommended torque		
Mating	**NA**	N.cm
Panel nut	**150**	N.cm
Mating life	**100**	Cycles mini
Weight	**6.970**	g

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SOLDER PROCEDURE

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
   We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.

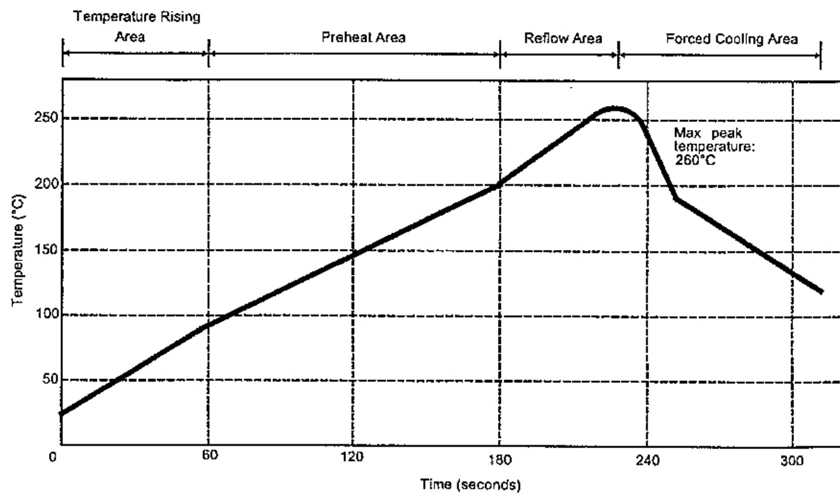
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

3. Soldering by infra-red reflow.

4. Cleaning of printed circuit boards.

5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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